BZT52BXXX

Rev.H Jan.-2024

DATA SHEET

5 é / Descriptions

SOD-123 .> / / x l 9 8 â ’ož

Zener Diode in a SOD-123 Plastic Package.

¤ ª / Features

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500mW power dissipation, medium current, automated assembly processes, HF Product.

Ð ÷ / Applications

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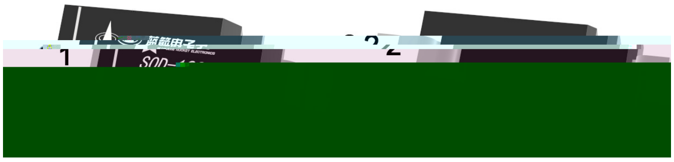
2.4V to 39V wide zener voltage range applications.



PIN1:Cathode PIN2:Anode

, M V / Marking

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See Marking Instructions.

@ ƒ Parameter	… Z Symbol	ƒ › Rating	% y Unit
Forward Voltage (Note 2) I_F=10mA	V_F	0.9	V
Power Dissipation(Note 1)	P_D	500	mW
Typical Thermal Resistance Junction to Ambient(Note 1)	R $_{JA}$	305	/W
Junction and Storage Temperature Range	T_j,T_{stg}	-65 150	

Type Number	Mark-ing Code	Zener Voltage Range				Maximum Zener Impedance			Maximum Reverse Current	
		V_Z @I_{ZT}			I_{ZT}	Z_{ZT} @I_{ZT}	Z_{ZK} @I_{ZK}	I_{ZK}	I_R	@V_R
		Nom (V)	Min (V)	Max (V)	mA			mA	A	V

[redacted]

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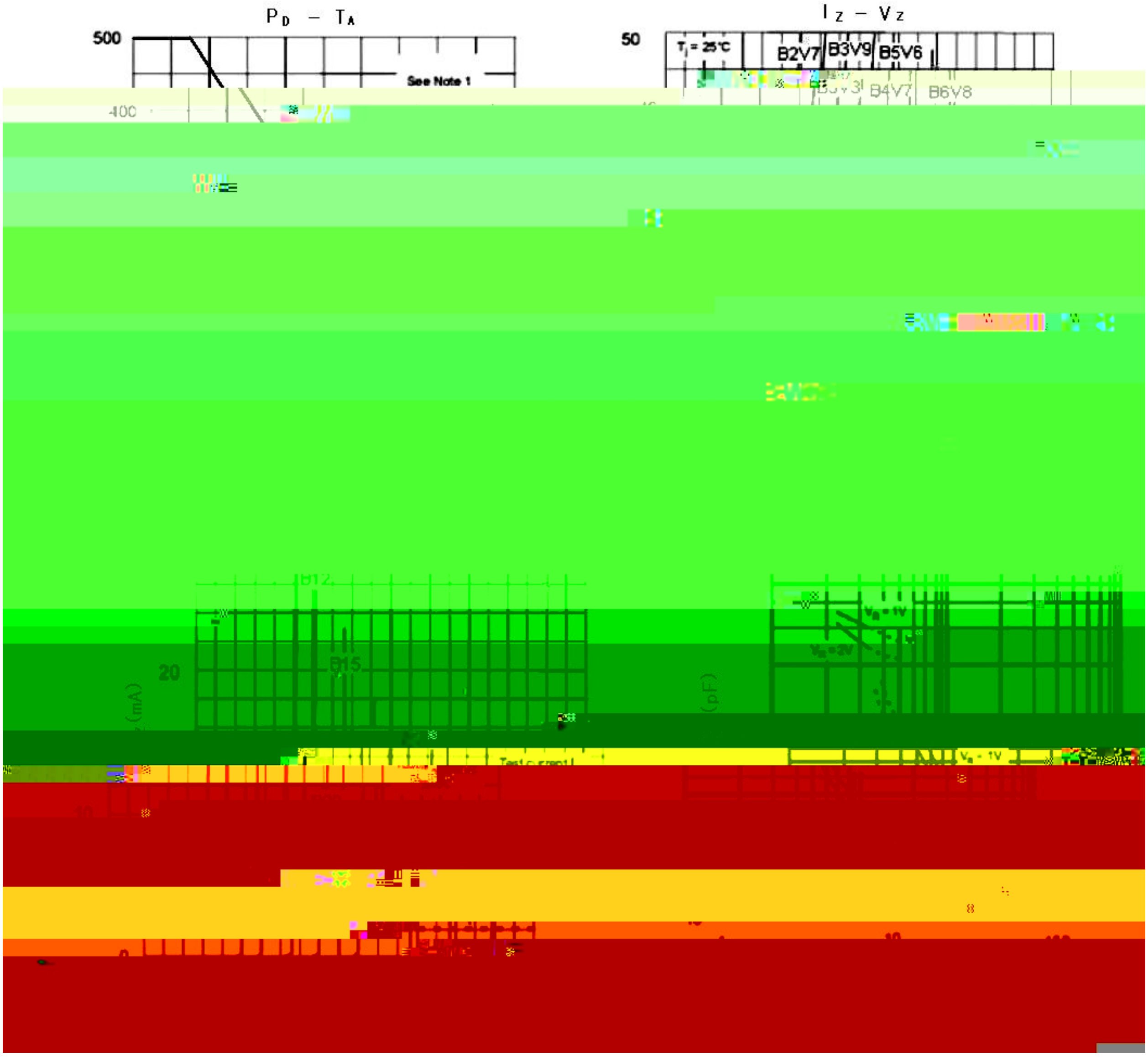
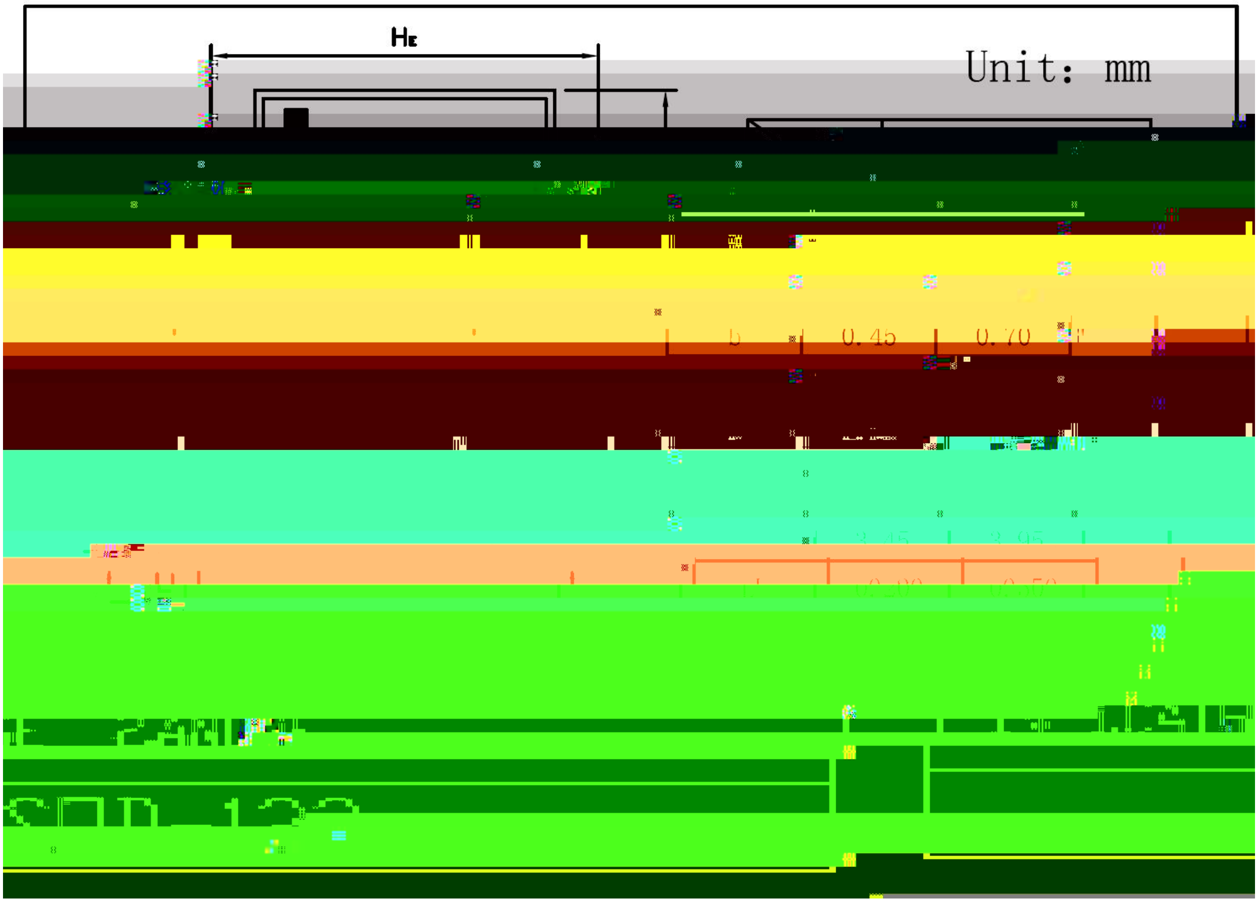
Notes:

1. Device mounted on ceramic PCB; 7.6mm x 9.4mm x 0.87mm with pad areas 25mm^2.
2. Short duration test pulse used to minimize self-heating effect.
3. f = 1kHz.

Ô ? d • Ž ¢ / Electrical Characteristic Curve



Ø ¤ =) ¢ / Package Dimensions



šWD t...•Ž¢ (x/) / :KSVKXGZ[XK 6XULORK LUX /8 8KLRU] 9URJKXOTM 6

ª ¢ y
1o• Ä ½ “ † 150 ½180 - k ž • 60 ½90sec;
2o• Q › “ † 245 r5 - k ž • 4 Ò 5 r0.5sec;
3o•D N ò i Ò 0 , † 2 ½10 - /sec.

Note:
1.Preheating:150~180 - , Time:60~90sec.
2.Peak Temp.:245 r5 - , Duration:5 r0.5sec.
3. Cooling Speed: 2~10 - /sec.

ÂD /Cã p ¯ »] / Resistance to Soldering Heat Test Conditions

“ † y 260 r5 - ž • y 10 r1 sec.

Temp.:260±5 Time:10±1 sec

G P á / Packaging SPEC.

2 & x / REEL

Package Type 7>û ˜ E	Units ;>û ¦H	Dimension ;>û p . (unit Æmm^3)